

SOT1456-1

plastic very-very-thin fine-pitch ball grid array package; 155 balls, 0.5 mm pitch, 7.5 mm x 7.5 mm x 0.76 mm body

29 October 2018

Package information

1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	WFBGA155
Package style descriptive code	BGA (ball grid array)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	06-04-2016
Manufacturer package code	SOT1456

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	7.4	7.5	7.6	mm
package width	7.4	7.5	7.6	mm
seated height	0.72	0.76	0.8	mm
package height	0.48	0.51	0.54	mm
nominal pitch	-	0.5	-	mm
actual quantity of termination	-	155	-	



3 Soldering

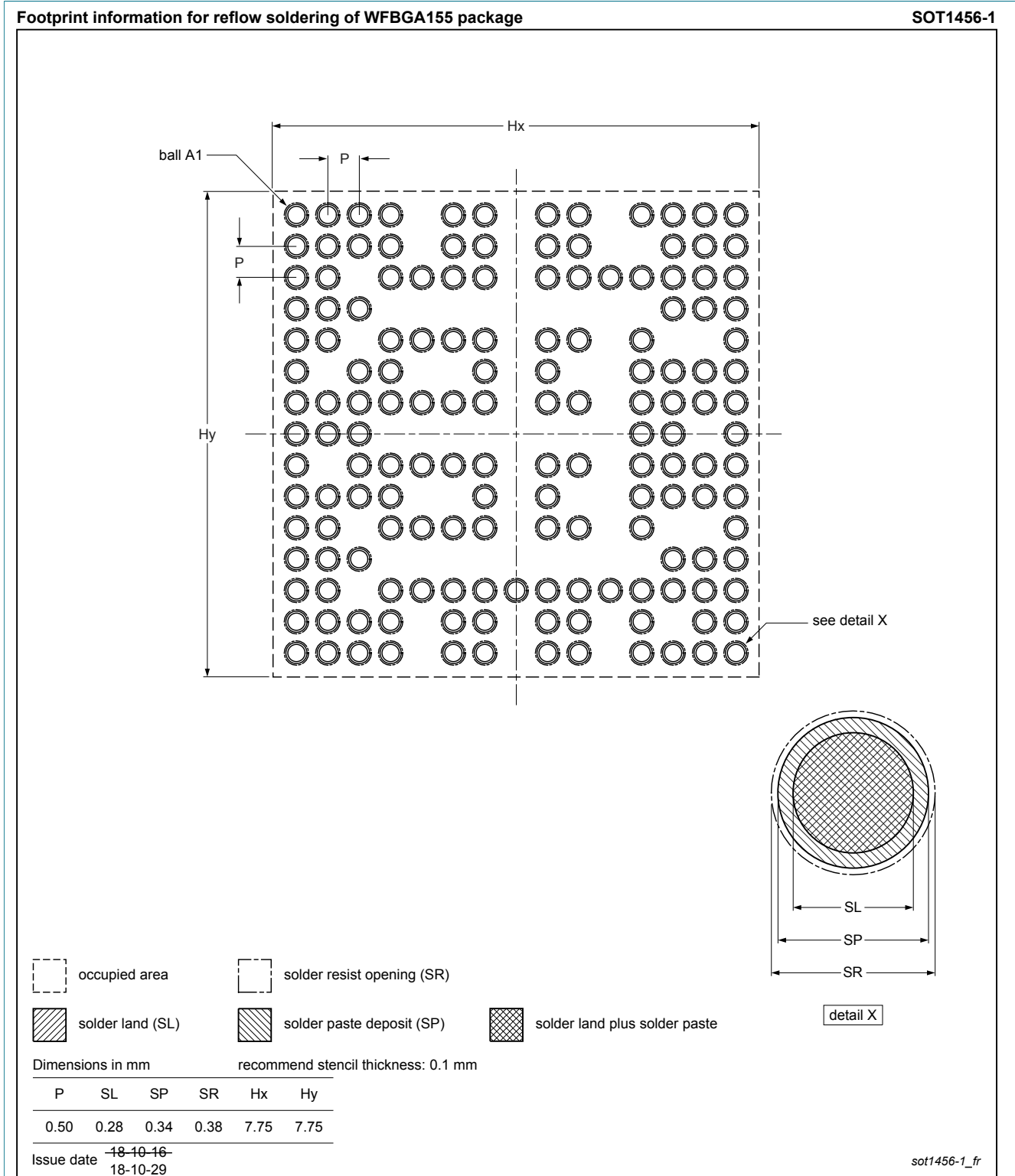


Figure 2. Reflow soldering footprint for WFBGA155 (SOT1456-1)

4 Legal information

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